1000V 3A N-Channel Enhancement Mode Power MOSFET

General Description

BXP3N1K is Bridgelux high voltage MOSFET family based on advanced planar DMOS technology. This advanced MOSFET family has optimized on-state resistance, and also provides superior switching performance and higher avalanche energy strength. This device family is suitable for high efficiency switch mode power supplies.

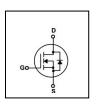
FEATURES

- RDSON \leq 6.0 Ω @Vgs=10V, Id=1.5A
- Excellent RDS(ON) and Low Gate Charge

Version: 1.2

- · Fast switching capability
- · Lead free product is acquired

SYMBOL









TO-251L

TO-252

TO-220F

ASSEMBLY MESSAGE

Product Name	Package	Packaging
BXP3N1KU	TO-251L	Tube
BXP3N1KD	TO-252	Tube/Reel
BXP3N1KF	TO-220F	Tube

ABSOLUTE MAXIMUM RATINGS (T_C=25°C unless otherwise noted)

Parameter		Symbol	Rating		Unit
			BXP3N1KU/ BXP3N1KI	BXP3N1KF	Unit
Drain-Source Voltage		V _{DSS}	1000		V
Drain Current	Continuous (T _C = 25°C)		3		Α
Drain Current	Continuous (T _C = 100°C)	- I _D	1.6		Α
Drain Current	Pulsed (Note1)	I _{DM}	12		Α
Gate-Source Voltage		V _{GSS}	±30		V
Avalanche Energy	Single Pulse (Note2)	Eas	120		mJ
Avalanche Current (Note1)		I AR	3		Α
Peak Diode Recovery dv/dt (Note3)		dv/dt	4.5		V/ns
Power Dissipation (Note	T _C =25°C	P _D	90	25	W
2)	Derate above 25°C		0.72	0.2	W/°C
Maximum Junction Temperature		TJ	150		°C
Storage Temperature Range		T _{STG}	-55 to 150		°C

- Note: 1. Repetitive Rating: Pulse width limited by maximum junction temperature
 - 2. L=25mH,V_{DD}=50V, RG=25 Ω , Starting TJ = 25°C
 - 3. $I_{SD} \le 3.0A$, $di/dt \le 300A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting TJ = 25°C





THERMAL CHARACTERISTICS

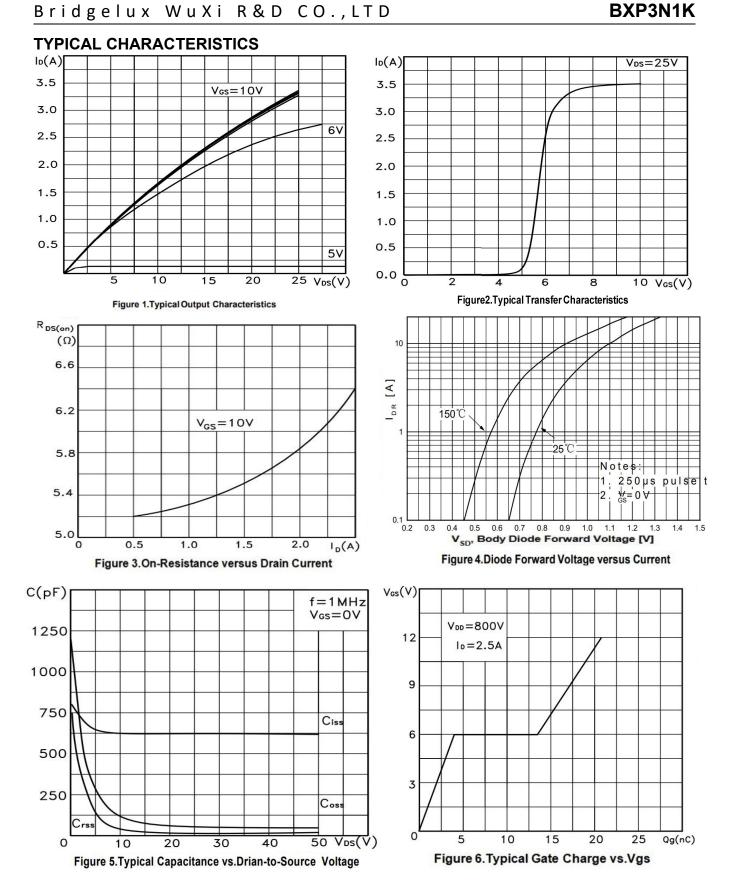
Downwater	Symbol	Max.	11:4	
Parameter		BXP3N1KU/ BXP3N1KD	BXP3N1KF	Unit
Thermal Resistance, Junction-to-Case	R _{θJC}	1.39	5	°C / W
Thermal Resistance, Junction-to-Ambient	R _{θJA}	62.5	62.5	°C/W

$\textbf{ELECTRICAL CHARACTERISTICS} \hspace{0.1cm} (T_J = 25 ^{\circ}\!C, unless \hspace{0.1cm} otherwise \hspace{0.1cm} Noted)$

Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit
OFF CHARACTERISTICS				•		
Drain-Source Breakdown Voltage	BV _{DSS}	VGS=0V, ID=250μA	1000			V
Zero Gate Voltage Drain Current	I _{DSS}	VDS=1000V, VGS=0V			1	uA
		VDS=800V, TC = 125°C			100	uA
Gate-Body Leakage Current, Forward		VGS=30V			100	nA
Gate-Body Leakage Current, Reverse	- I _{GSS}	VGS=-30V			-100	nA
Breakdown Voltage Temperature	△BVDSS/	ID = 250 μA	0.00	0.00		V/°C
Coefficient	△TJ			0.98		
ON CHARACTERISTICS				•		•
Gate Threshold Voltage	V _{GS(TH)}	VDS=VGS, ID=250µA	3		4	V
Drain-Source On-State Resistance	R _{DS(ON)}	VGS=10V, ID=1.5A		4.8	6	Ω
Forward Transconductance (Note4)	g FS	VDS = 50V, ID=1.5A		9.4		S
DYNAMIC PARAMETERS						
Input Capacitance	C _{ISS}	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\		610		pF
Output Capacitance	Coss	VDS=25V, VGS=0V, f=1.0MHz		55		pF
Reverse Transfer Capacitance	Crss	I-I.UIVINZ		14		pF
SWITCHING PARAMETERS						
Turn-ON Delay Time	t _{D(ON)}	\/DD_500\/ ID_2A_\/CC		15		ns
Turn-ON Rise Time	t _R	VDD=500V, ID=3A, VGS = 10V ,RG=10Ω		7.6		ns
Turn-OFF Delay Time	t _{D(OFF)}	(Note4,5)		40		ns
Turn-OFF Fall-Time	t⊧	(110164,5)		31		ns
Total Gate Charge(Note5)	Q_{G}	VDS =800V, VGS =10V,		18		nC
Gate Source Charge	Q _{GS}	ID =2.5A		3.8		nC
Gate Drain Charge	Q_{GD}	(Note4,5)		9.5		nC
SOURCE- DRAIN DIODE RATINGS	AND CHARA	ACTERISTICS				
Drain-Source Diode Forward Voltage	V _{SD}	IS=3A, VGS=0V			1.4	V
Diode Continuous Forward Current	Is				3	Α
Pulsed Drain-Source Current	I _{SM}				12	Α
Reverse Recovery Time	t _{RR}	VGS = 0 V, ISD = 3A		580		ns
Reverse Recovery Charge	Q _{RR}	di/dt=100 A/µs (Note4,5)		2.3		uC

Note: 4. Pulse Test : Pulse width ≤ 300µs, Duty cycle ≤ 2%

^{5.} Essentially independent of operating temperature



TYPICAL CHARACTERISTICS(Cont.)

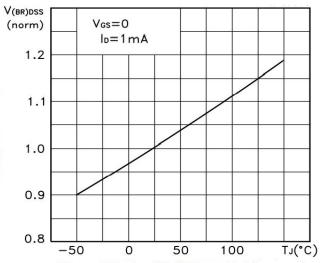


Figure 7.Bvdss Variation with Temperature

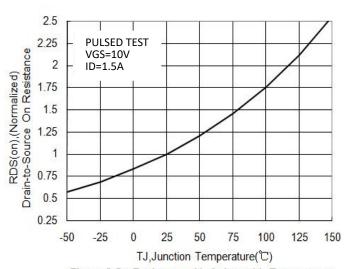
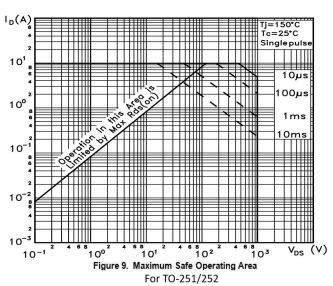
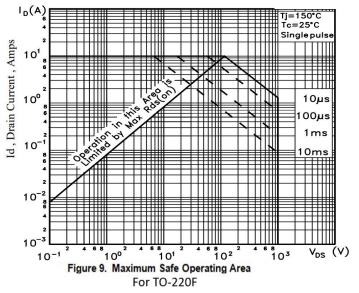
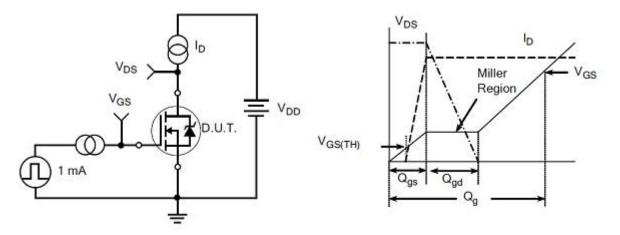


Figure 8.On-Resistance Variation with Temperature



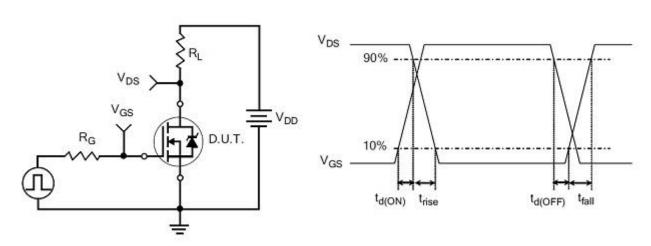


TEST CIRCUITS AND WAVEFORMS



Gate Charge Test Circuit

Gate Charge Waveform

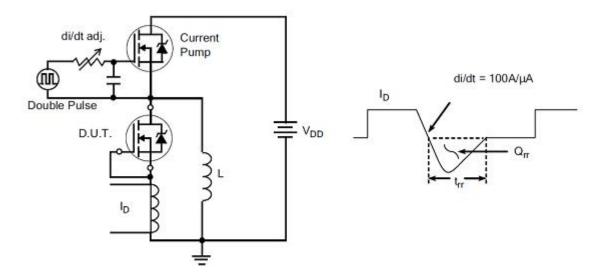


Resistive Switching Test Circuit

Resistive Switching Waveforms

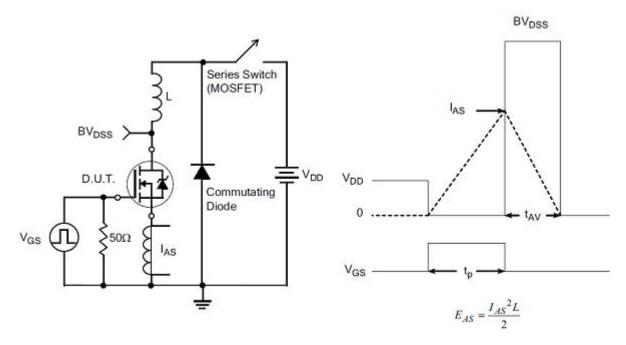


TEST CIRCUITS AND WAVEFORMS(Cont.)



Diode Reverse Recovery Test Circuit

Diode Reverse Recovery Waveform



Unclamped Inductive Switching Test Circuit

Unclamped Inductive Switching Waveforms





Revision history

Document revision history

Date	Revision	Changes
1-Jul-2021	1.0	First release
8-Dec-2021	1.1	Update layout format
5-Jan-2022	1.2	Update parameter





BXP3N1K

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